

CMKD6001

**SURFACE MOUNT
TRIPLE ISOLATED
ULTRA LOW LEAKAGE
SILICON SWITCHING DIODES**



www.centrasemi.com

ULTRAmulti™



SOT-363 CASE

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKD6001 type contains three (3) Isolated Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a ULTRAmulti™ surface mount package, designed for switching applications requiring extremely low leakage.

MARKING CODE: K01

MAXIMUM RATINGS: (T_A=25°C)

Continuous Reverse Voltage
 Peak Repetitive Reverse Voltage
 Continuous Forward Current
 Peak Repetitive Forward Current
 Peak Forward Surge Current, t_p=1.0μs
 Peak Forward Surge Current, t_p=1.0s
 Power Dissipation
 Operating and Storage Junction Temperature
 Thermal Resistance

SYMBOL

V_R 75
 V_{RRM} 100
 I_F 250
 I_{FRM} 500
 I_{FSM} 4.0
 I_{FSM} 1.0
 P_D 250
 T_J, T_{stg} -65 to +150
 Θ_{JA} 500

UNITS

V
 V
 mA
 mA
 A
 A
 mW
 °C
 °C/W

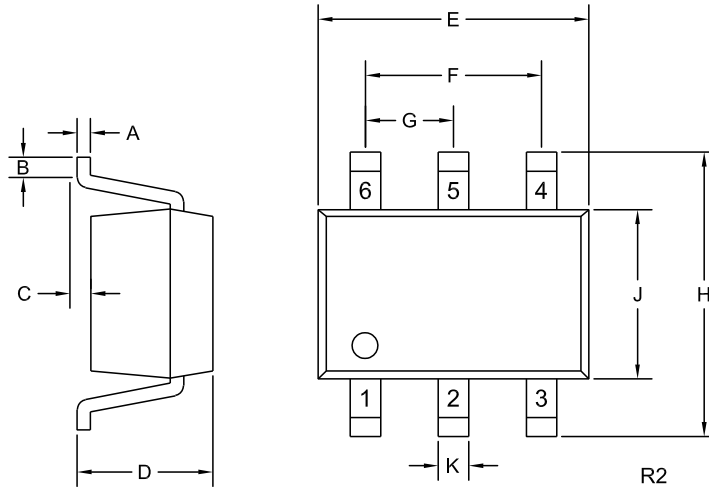
ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _R	V _R =75V		500	pA
BV _R	I _R =100μA	100		V
V _F	I _F =1.0mA		0.85	V
V _F	I _F =10mA		0.95	V
V _F	I _F =100mA		1.1	V
C _T	V _R =0, f=1.0MHz		2.0	pF
t _{rr}	I _R =I _F =10mA, I _{rr} =1.0mA, R _L =100Ω		3.0	μs

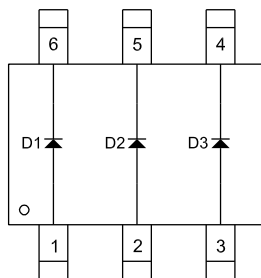
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SOT-363 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.004	0.010	0.10	0.25
B	0.005	-	0.12	-
C	0.000	0.004	0.00	0.10
D	0.031	0.043	0.80	1.10
E	0.071	0.087	1.80	2.20
F	0.051		1.30	
G	0.026		0.65	
H	0.075	0.091	1.90	2.30
J	0.043	0.055	1.10	1.40
K	0.006	0.012	0.15	0.30

SOT-363 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) Anode D2
- 3) Anode D3
- 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

MARKING CODE: K01

R5 (9-May 2011)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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